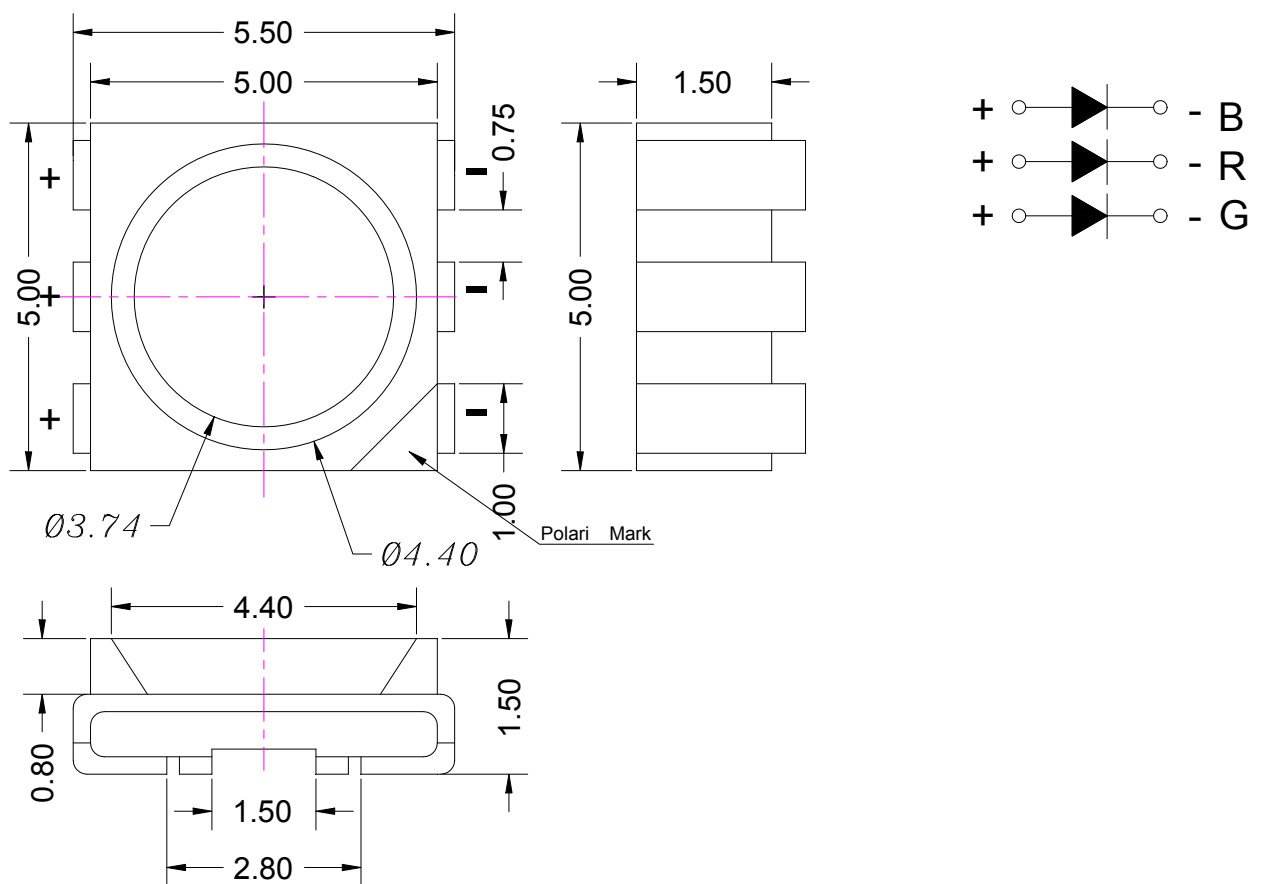




Wen Li	Fang Yang	Jiang Yang	Fang Wang



Tolerance: 0.25(0.01)



Uni mm

Color RGB

Len -color Wa er clear

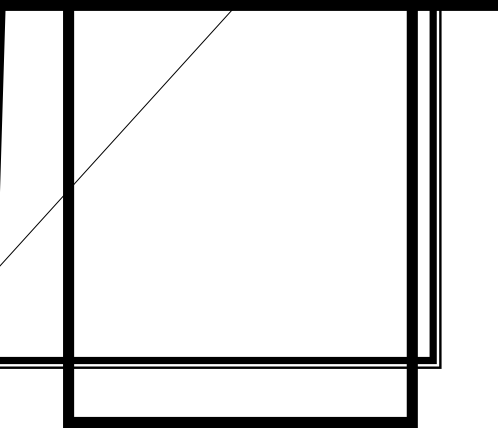
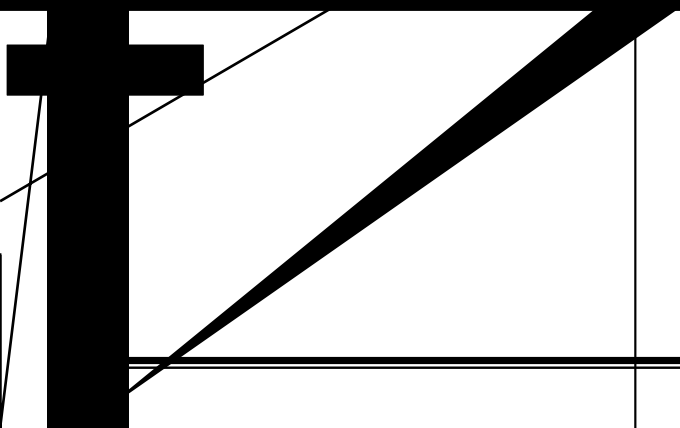
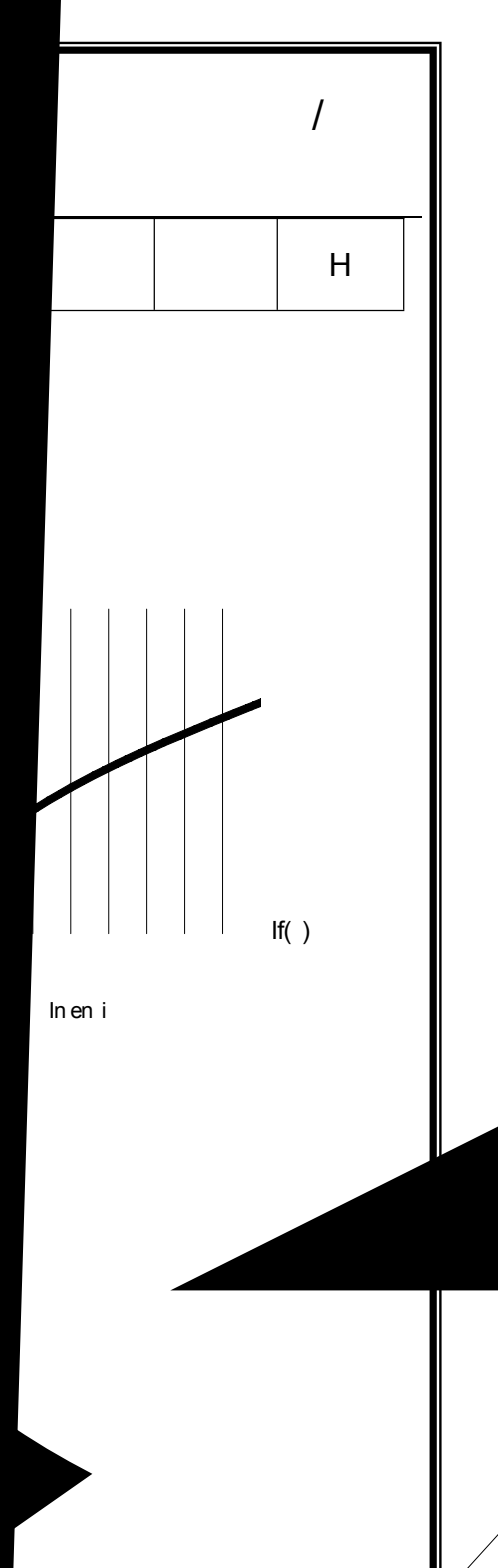
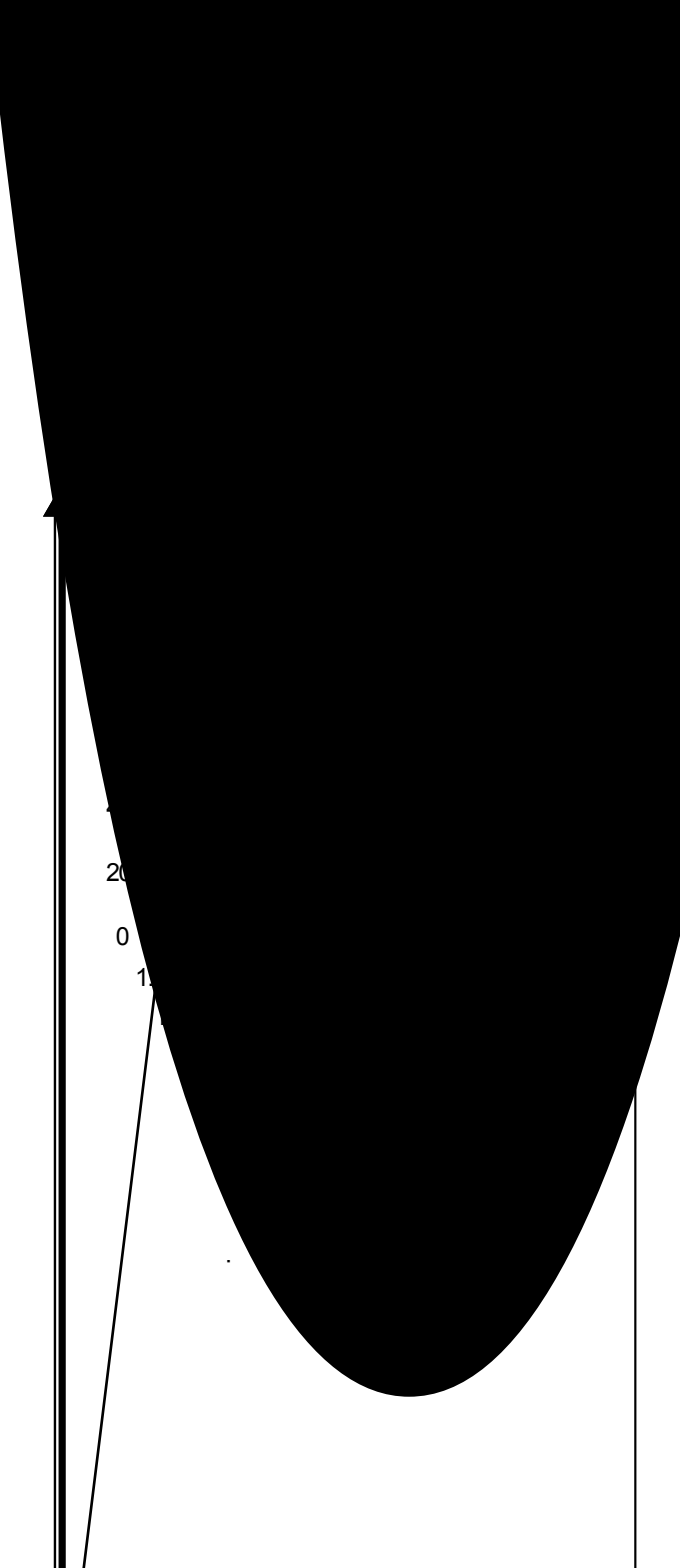
Emi ing Ma erial InGaN

Dra ing b oli a ion



3 Characteristic

Forward current	If	30	mA			
Reverse voltage	Vr	5	V			
Power dissipation	Pd	110	mW			
Operating temperature range	Top	-25 +80	C			
Storage temperature range	T g	-30 +80	C			
Peak pulsed current 1/8 d f=1KH	Ifp	125	mA			
Wavelength at peak emission (R)	If=20mA	peak	620	625	630	nm
Wavelength at peak emission (G)			515	520	525	
Wavelength at peak emission (B)			460	465	470	
Spectral half bandwidth	If=20mA			10		
Forward voltage (R)	If=20mA	Vf	1.8	2.0	2.4	V
Forward voltage (G)			3.0	3.3	3.6	
Forward voltage (B)			3.0	3.3	3.6	
Luminous intensity (R)	If=20mA	I	800	1000	1200	mcd
Luminous intensity (G)			3000	3500	4000	
Luminous intensity (B)			400	500	600	
Viewing angle at 50% IV	If=10mA		--	120	--	Deg
Reverse current	Vr=5V	Ir	--	--	5	A



Assembly

i Iron Soldering: The Iron (max 30W) end temperature less than 300 °C, soldering time 3 seconds, soldering position is minimum 2mm from board.

ii Dip Soldering: Max temperature 260 °C, time 5s, solder position is minimum 2mm from board.

i Bracket must be bent only if 2mm from colloid.

ii Bracket mould must be finished before or post soldering.

iii Bracket mould must be finished before soldering.

i Bracket mould should adhere the connection between the pin, the distance gap of lead and the circuit board.

i. It should be paid attention to the ordering of all the devices in case of wrong polarity. Devices can be too close to the heat component, working condition can replace the limit.

ii. It should not assemble LED when the lead is deformed.

iii. When decide to assemble in hole, according to the position of hole and hole distance of the line base

i. Suggesting glue heat protection

i. d p rtd

